RS-485 To Wi-Fi Bridge with 24 VAC Power

Project Title:

Designed for:

Public Release

Assembly Variant:

002

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Drawn By:

Engineer:

M. Knapp

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Version control disabled

SVN Rev:

ISE4037

Number:

Rev:

E3

TID #:

TIDA-00485

Orderable:

N/A

Revision History

Revision Notes

E3: Added Drill Table to FAB drawing.
E2: Updated Footprint for L1, C9 changed to 4.7nF

*Convert to Buck for Non-Isolated Version

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E3: Added Drill Table to FAB drawing.
E2: Updated Footprint for L1, C9 changed to 4.7nF

*Convert to Buck for Non-Isolated Version
Variant Key:

Variant 001 has an isolated RS-485 interface and a Fly-Buck power supply with an isolated secondary.

Variant 002 has a non-isolated RS-485 interface and a simple Buck power supply.
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NON-ISOLATED TRANSCEIVER

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These assemblies are ESD sensitive, ESD precautions shall be observed.

These assemblies must be clean and free from flux and all contaminants. Use of no-clean flux is not acceptable.

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Place SH-J6 on J6, SH-J7 on J7, and SH-J9 on J9.
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